



*Open up your dreams*

**FOR IMMEDIATE RELEASE**

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**ZyCube and OKI Sign Agreement to Commercialize Image Sensors for  
Wafer-level CSP with Buried Interconnects  
- *The smallest, thinnest, and highest-density image sensor devices* -**

**Tokyo, Japan, January 24, 2007** – Oki Electric Industry Co., Ltd. (TSE: 6703) and ZyCube Co., Ltd. today announced the agreement to cooperate in commercializing ZyCSP™, an image sensor LSI with buried interconnects (also called TSV (Through Silicon Via)) that is equivalent in size to a wafer level chip size package(CSP). Compared to current C-MOS and CCD sensor packages, the ZyCSP™ achieves thinner, smaller, lighter and highly reliable characteristics.

ZyCSP™ is the CSP for image sensors with buried interconnect technology developed by ZyCube. Plating and/or burying a hole through the sensor LSI wafer and applying wiring technology, the new technology without wire bonding made ZyCSP™ possible to be extremely high-density and low-profile which is less than 0.6mm, the world's thinnest CSP.

“Consumers desire information devices to be smaller, higher density with multi-functions as seen in camera-equipped mobile phones and digital cameras,” said Manabu Bonkohara, CEO of ZyCube. “Our strategy is to focus on the image sensor market for these devices for now, and eventually expand to the 3D compound product market with digital signal processing function. With our ZyCSP™ technology, we are determined not only to take 15% share of the world's C-MOS, CCD sensor market, but also standardize packaging technologies in the world.”

OKI, on the other hand holds advanced wafer level CSP (W-CSP) technology achieving packages equivalent to chip sizes. Through the collaboration, OKI will work to achieve smaller and thinner passive and active components taking advantage of its W-CSP and semiconductor processing technologies. It will also be possible for OKI to apply the new production technology for making LSIs having buried interconnections to its own products.

The two companies will jointly develop and manufacture packages for C-MOS and CCD sensors with buried interconnects. OKI will build a combination 8-inch/12-inch development and production line for ZyCSP™ at its Hachioji facility in Japan. According to the business scale, OKI will expand the production line.

“In addition to our current 6 and 8-inch W-CSP assembly foundry business, we will actively provide small and high-performance packaging solutions by expanding in to 12 inch with ZyCube,” said Takaki Yamada, President of Silicon Micro Device Company at Oki Electric Industry. “We will deploy business in the growing information device market with ZyCSP™ products, and remain committed to creating new applications in the ‘personal and mobile’ markets, and provide smaller, higher performance and lower power consumption products for mobile terminals. “

***About Oki Electric Industry Co., Ltd.***

Founded in 1881, Oki Electric Industry Co., Ltd. is Japan's first telecommunications manufacturer, with its headquarters in Tokyo, Japan. OKI provides top-quality products, technologies and solutions to its customers through its info-telecom system business, semiconductor business and printer business. All three businesses function as a collective force to create exciting new products and technologies that satisfy a spectrum of customer needs in various markets. Visit OKI's global web site at <http://www.oki.com/>.

***About ZyCube Co., Ltd.***

ZyCube was founded in 2002 to launch its advanced 3-D stacked SoC technology which brings a paradigm shift to semiconductor industry with new roadmaps for high-capacity, high-performance, smaller size, and low-power consumption devices. ZyCube applies its innovative wafer-on-wafer technology coupled with conventional chip-on-chip and chip-on-wafer technologies to meet various requirements of its strategic partners. Find more at <http://www.zy-cube.com/e>

Notes:

- ZyCSP is a trademark of ZyCube Co., Ltd.
- Names of companies and products are trademarks or registered trademarks of the respective companies and organizations.

**Cross sectional view of W-CSP  
with buried interconnects with ZyCSP™ technology**

